



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. PENDSE, *et al.*

Application No.: 10/081,491

Filed: February 22, 2002

Title: **Super-thin high speed flip chip package**

)  
) Examiner: Angel ROMAN  
)  
) Group Art Unit: 2812  
)  
) Date: May 1, 2003

) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 1, 2003.

Signed

Linda Shaw

COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

AMENDMENT

Dear Sir:

Responsive to the Office Action mailed November 1, 2002, kindly amend the application as follows.

In the Specification (Abstract)

Please amend the specification, as shown on the attached "Attachment under Rule 1.121", as follows.

Replace the Abstract with the following rewritten Abstract.

-- A flip chip package is formed by a solid-state bond technique for connecting the input/output pads on the integrated circuit chip and the package substrate. The solid-state bond technique involves a direct mating of metal surfaces, and does not employ any particulate conductive material nor any melting or flow of any interconnecting material. Accordingly the connections can be formed at very fine geometries. In another aspect, the space between the surface of the integrated circuit chip and the subjacent surface of the package substrate is filled with a patterned adhesive structure, which consists of one or more adhesive materials that are deployed in a specified pattern in relation to the positions of the second level interconnections between the package and the printed circuit board. --